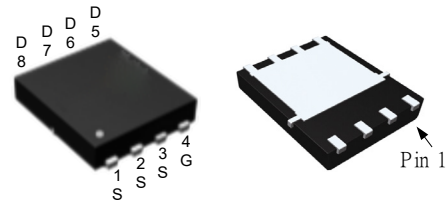


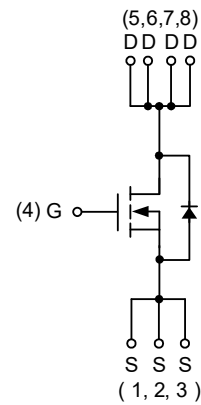
Features

- 40V/88A
 $R_{DS(ON)}=4m\Omega(\text{typ.})@V_{GS}=10V$
 $R_{DS(ON)}=5.5m\Omega(\text{typ.})@V_{GS}=4.5V$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free and Green Devices Available
 (RoHS Compliant)

Pin Description



PDFN5*6-8L



N-Channel MOSFET

Applications

- Power Management in Desktop Computer or DC/DC Converters.

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit	
Common Ratings				
V_{DSS}	Drain-Source Voltage	40	V	
V_{GSS}	Gate-Source Voltage	± 20		
T_J	Maximum Junction Temperature	175	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ\text{C}$	
I_S	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	88	A
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$	88	A
		$T_C=100^\circ\text{C}$	53	
I_{DM}^a	Pulse Drain Current	$T_C=25^\circ\text{C}$	264	A
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	68	W
		$T_C=100^\circ\text{C}$	34	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	2.2	$^\circ\text{C}/\text{W}$
$R_{\theta JA}^b$	Thermal Resistance-Junction to Ambient	$t \leq 10\text{s}$	25	$^\circ\text{C}/\text{W}$
		Steady State	64	
I_{AS}^c	Avalanche Current, Single pulse	$L=0.1\text{mH}$	40	A
E_{AS}^c	Avalanche Energy, Single pulse	$L=0.1\text{mH}$	80	mJ

Note a : Pulse width is limited by max. junction temperature.

Note b : Surface mounted on 1in^2 pad area, steady state $t = 999\text{s}$.

Note c : UIS tested and pulse width limited by maximum junction temperature (initial temperature $T_j=25^\circ\text{C}$).

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

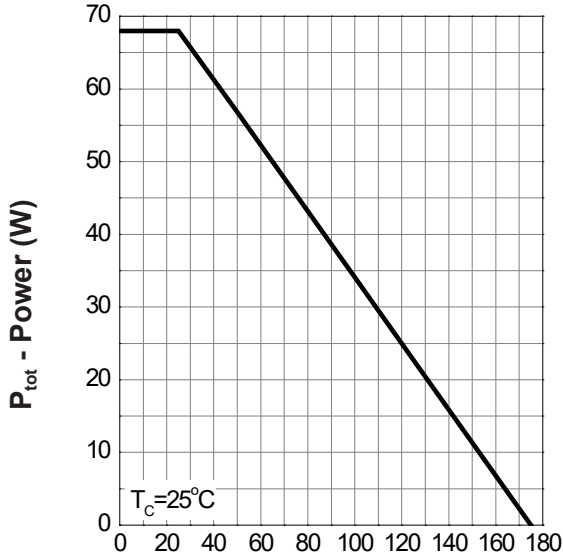
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=32V, V_{GS}=0V$ $T_J=85^\circ\text{C}$	-	-	1	μA
			-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1.4	1.8	2.5	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
$R_{DS(on)}^d$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=20A$ $T_J=125^\circ\text{C}$	-	4	5.3	m Ω
			-	6.3	-	
		$V_{GS}=4.5V, I_{DS}=15A$	-	5.5	7.6	
Gfs	Forward Transconductance	$V_{DS}=5V, I_{DS}=15A$	-	25	-	S
Diode Characteristics						
V_{SD}^d	Diode Forward Voltage	$I_{SD}=20A, V_{GS}=0V$	-	0.85	1.1	V
t_{rr}	Reverse Recovery Time	$I_{DS}=20A, di_{SD}/dt=100A/\mu s$	-	25	-	ns
t_a	Charge Time		-	15	-	
t_b	Discharge Time		-	10	-	
Q_{rr}	Reverse Recovery Charge		-	15	-	
Dynamic Characteristics [°]						
R_G	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	1	2	Ω
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=20V,$ Frequency=1.0MHz	-	980	-	pF
C_{oss}	Output Capacitance		-	317	-	
C_{rss}	Reverse Transfer Capacitance		-	46	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=20V, R_L=20\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$	-	13.3	24	ns
t_r	Turn-on Rise Time		-	7.9	15	
$t_{d(OFF)}$	Turn-off Delay Time		-	29.1	53	
t_f	Turn-off Fall Time		-	21	38	
Gate Charge Characteristics [°]						
Q_g	Total Gate Charge	$V_{DS}=20V, V_{GS}=10V,$ $I_{DS}=20A$	-	22	30.8	nC
Q_{gth}	Threshold Gate Charge		-	2.3	-	
Q_{gs}	Gate-Source Charge		-	4.2	-	
Q_{gd}	Gate-Drain Charge		-	3	-	

Note d : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

Note e : Guaranteed by design, not subject to production testing.

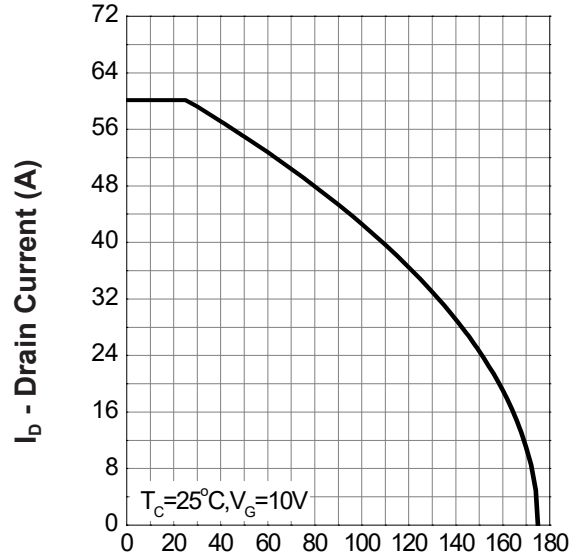
Typical Operating Characteristics

Power Dissipation



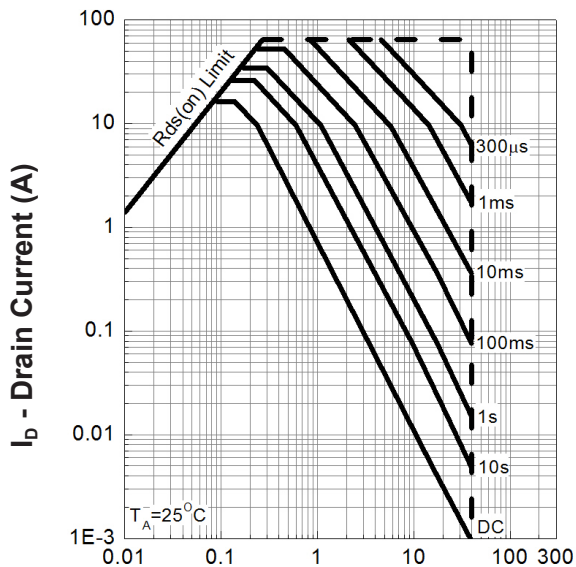
T_c - Case Temperature ($^\circ\text{C}$)

Drain Current



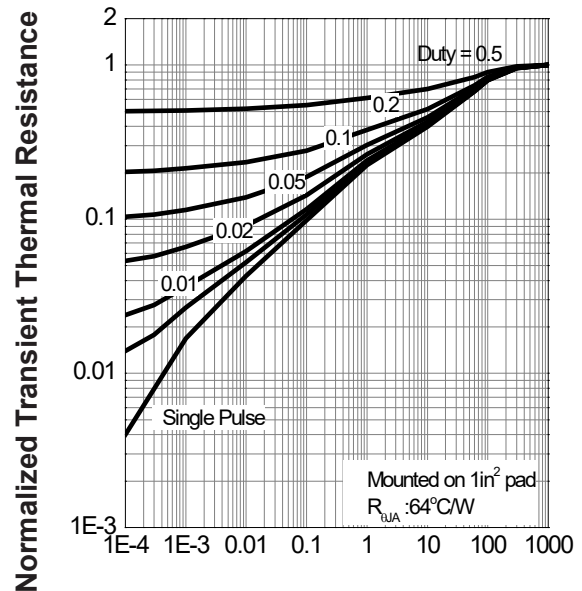
T_c - Case Temperature ($^\circ\text{C}$)

Safe Operation Area



V_{DS} - Drain - Source Voltage (V)

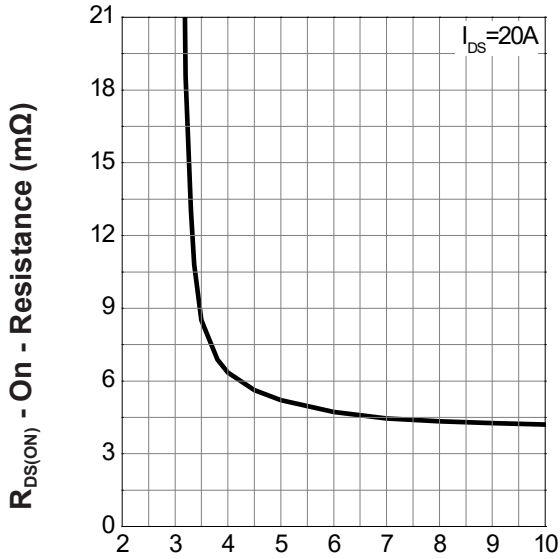
Thermal Transient Impedance



Square Wave Pulse Duration (sec)

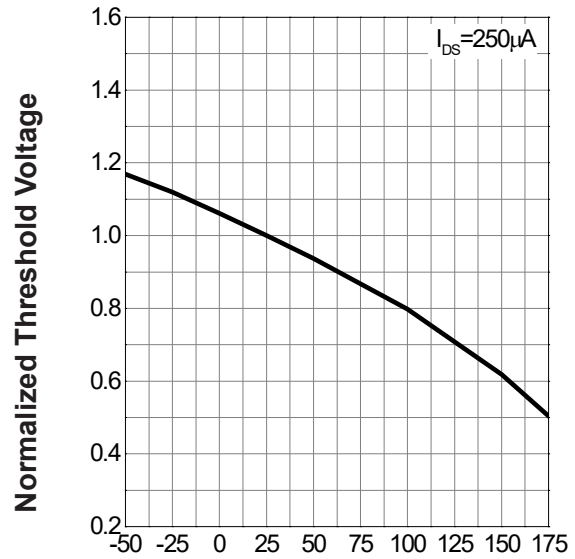
Typical Operating Characteristics(Cont.)

Gate-Source On Resistance



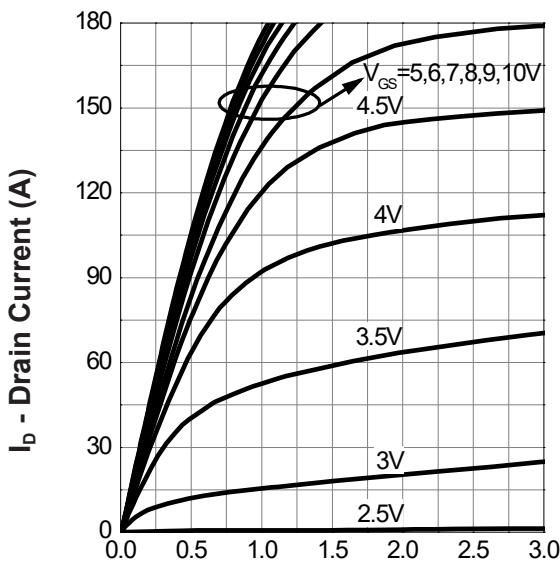
V_{GS} - Gate - Source Voltage (V)

Gate Threshold Voltage



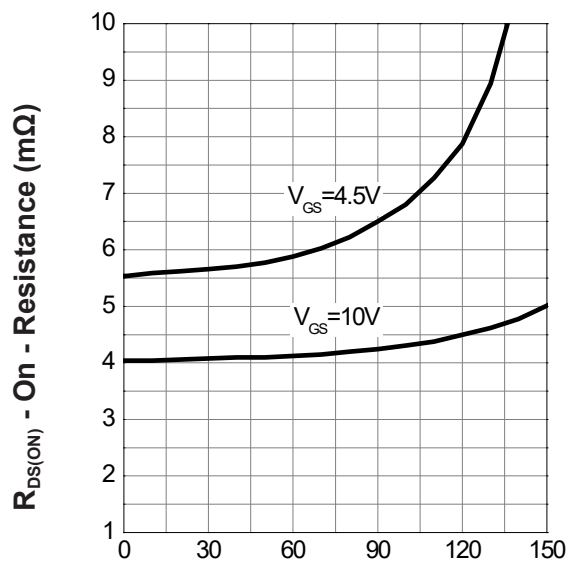
T_J - Junction Temperature (°C)

Output Characteristics



V_{DS} - Drain - Source Voltage (V)

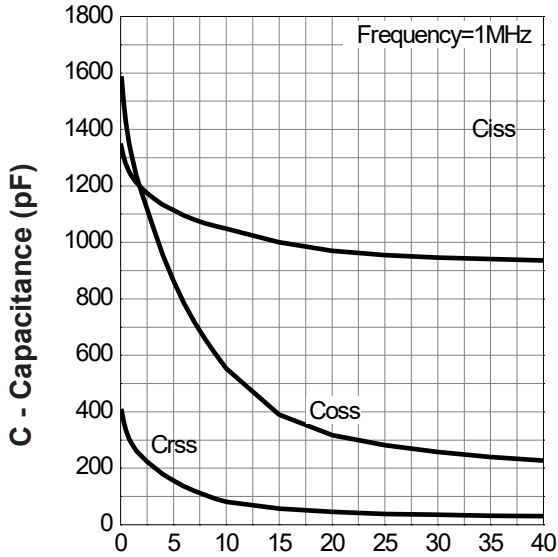
Drain-Source On Resistance



I_D - Drain Current (A)

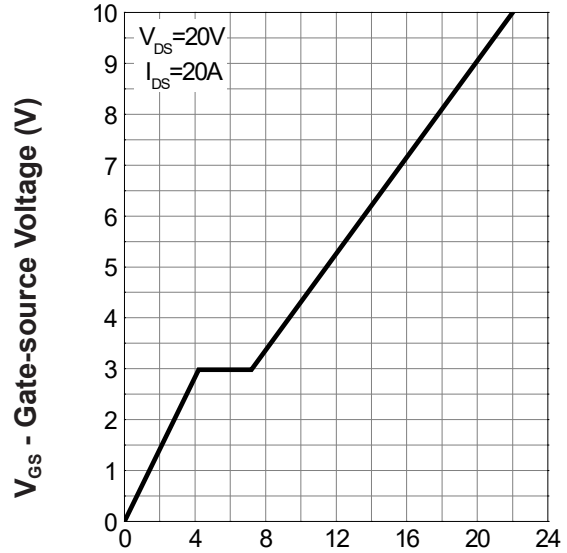
Typical Operating Characteristics(Cont.)

Capacitance



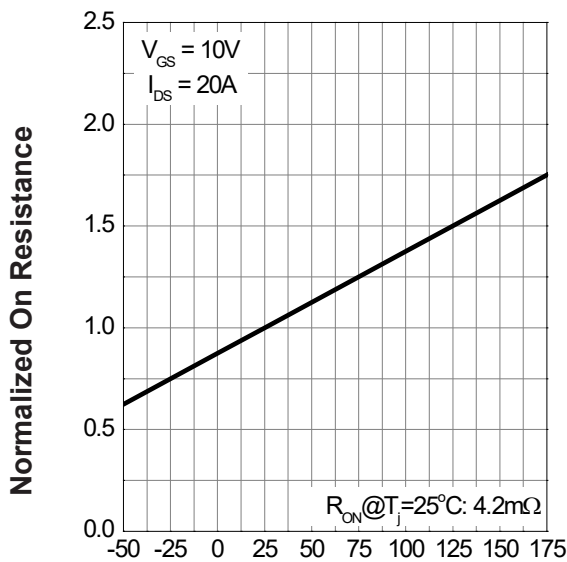
V_{DS} - Drain-Source Voltage (V)

Gate Charge



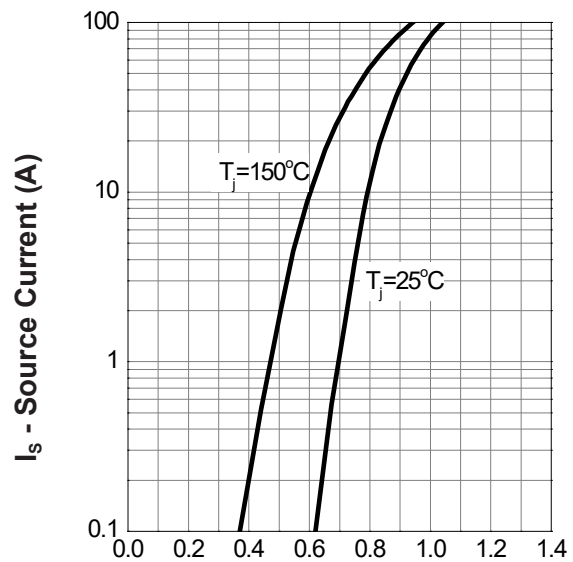
Q_G - Gate Charge (nC)

Drain-Source On Resistance



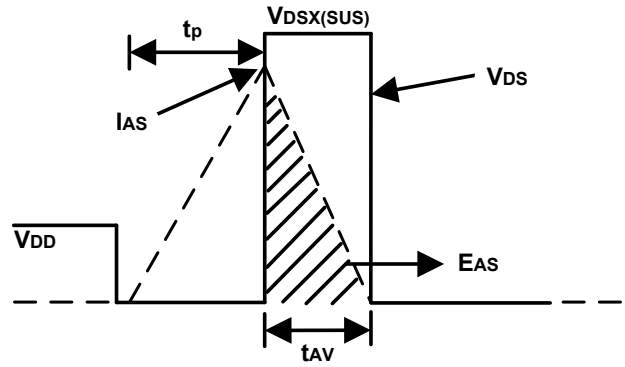
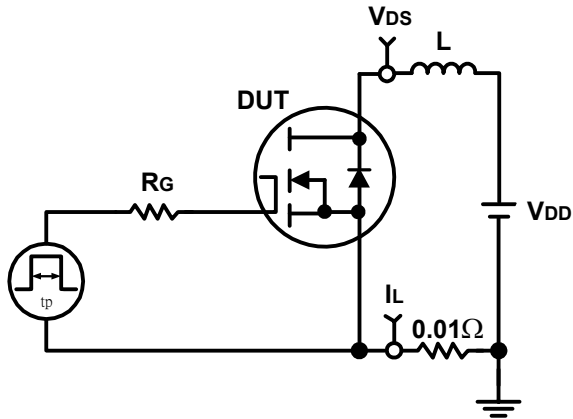
T_j - Junction Temperature ($^\circ C$)

Source-Drain Diode Forward

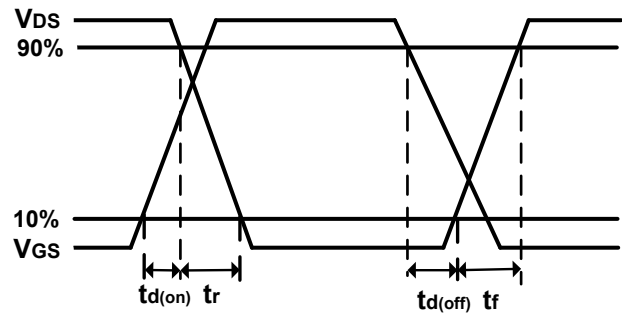
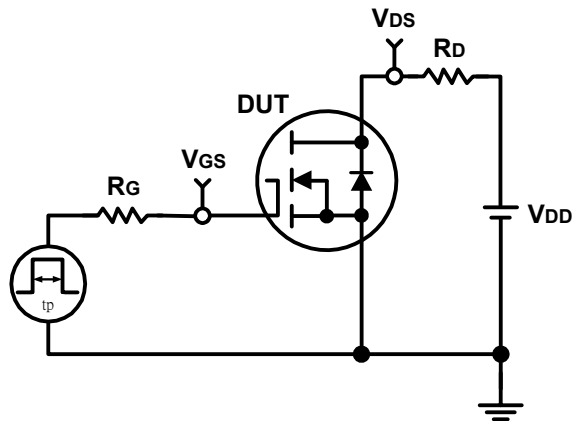


V_{SD} - Source - Drain Voltage (V)

Avalanche Test Circuit and Waveforms

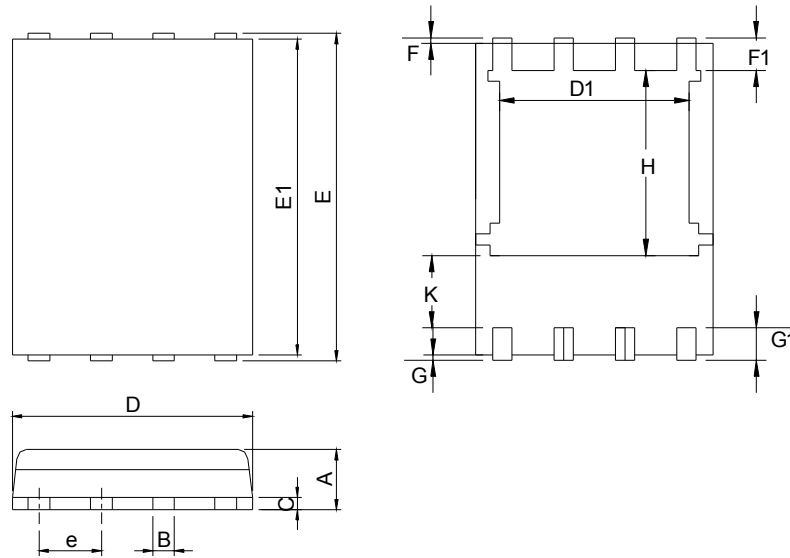


Switching Time Test Circuit and Waveforms



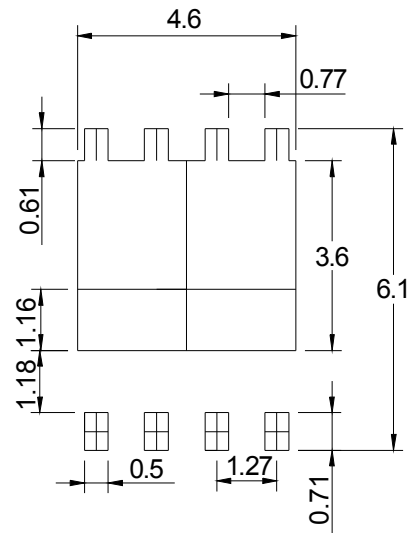
Package Information

PDFN5*6-8L



DIMENSIONS	PDFN5*6-8L			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.90	1.20	0.035	0.047
B	0.3	0.51	0.012	0.020
C	0.19	0.25	0.007	0.010
D	4.80	5.30	0.189	0.209
D1	4.00	4.40	0.157	0.173
E	5.90	6.20	0.232	0.244
E1	5.50	5.80	0.217	0.228
e	1.27 BSC		0.050 BSC	
F	0.05	0.30	0.002	0.012
F1	0.35	0.75	0.014	0.030
G	0.05	0.30	0.002	0.012
G1	0.35	0.75	0.014	0.030
H	3.34	3.9	0.131	0.154
K	0.762	-	0.03	-

RECOMMENDED LAND PATTERN



UNIT: mm

Note : 1.Dimension D, D1,D2 and E1 do not include mold flash or protrusions.
Mold flash or protrusions shall not exceed 10 mil.